

Part Number: WP63SRD

Super Bright Red

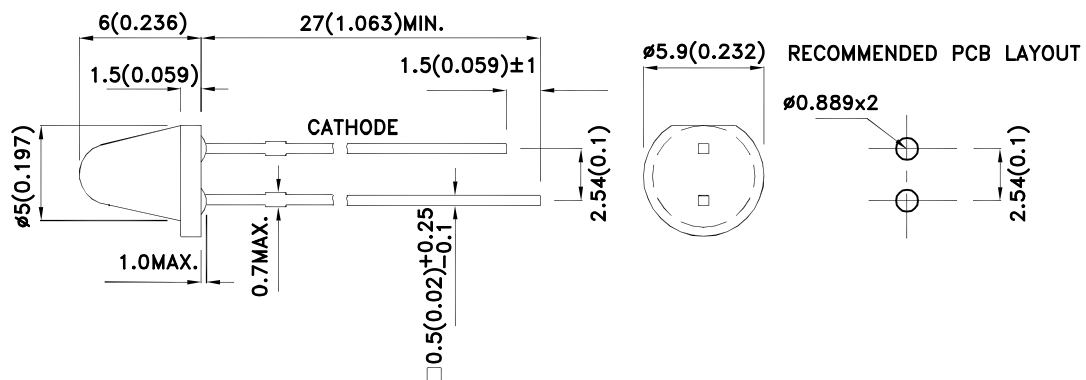
Features

- Low profile.
- Low power consumption.
- Long life - solid state reliability.
- Reliable and rugged.
- RoHS compliant.

Description

The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
WP63SRD	Super Bright Red (GaAlAs)	Red Diffused	150	300	60°
			*50	*100	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.
- * Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Red	655		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Red	640		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Red	20		nm	IF=20mA
C	Capacitance	Super Bright Red	45		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Red	1.85	2.5	V	IF=20mA
IR	Reverse Current	Super Bright Red		10	uA	VR = 5V

Notes:

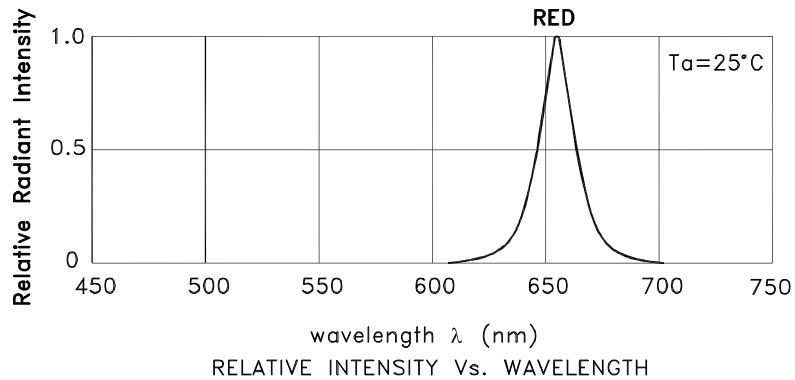
- 1.Wavelength: +/-1nm.
- 2.Forward Voltage: +/-0.1V.
- 3.Wavelength value is traceable to the CIE127-2007 compliant national standards.
- 4.Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Red	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	155	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	
Lead Solder Temperature [2]	260°C For 3 Seconds	
Lead Solder Temperature [3]	260°C For 5 Seconds	

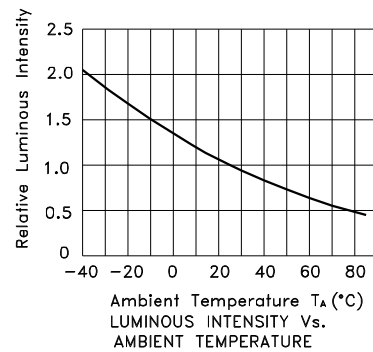
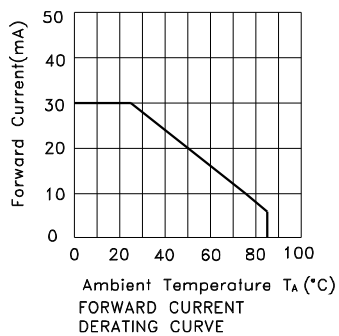
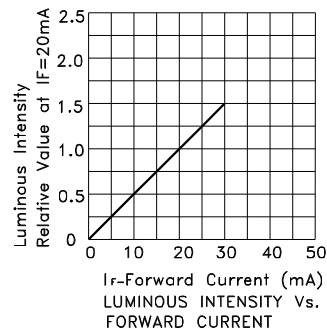
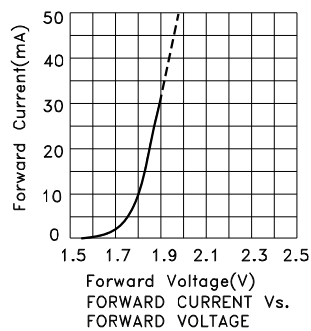
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.



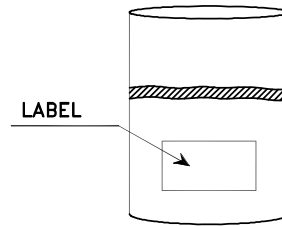
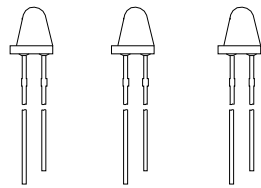
Super Bright Red

WP63SRD



PACKING & LABEL SPECIFICATIONS

WP63SRD



500PCS / BAG

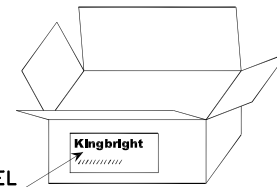


32K / 9# BOX

OUTSIDE LABEL



OUTSIDE LABEL



16K / 5# BOX

Kingbright	
P/NO: WP63xxx	
QTY: 500 pcs	Q.C. Q C XX XX XX PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	

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PRECAUTIONS

1. Storage conditions:

- Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
- LEDs should be stored with temperature $\leq 30^{\circ}\text{C}$ and relative humidity $< 60\%$.
- Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at $85 \sim 100^{\circ}\text{C}$.

2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)

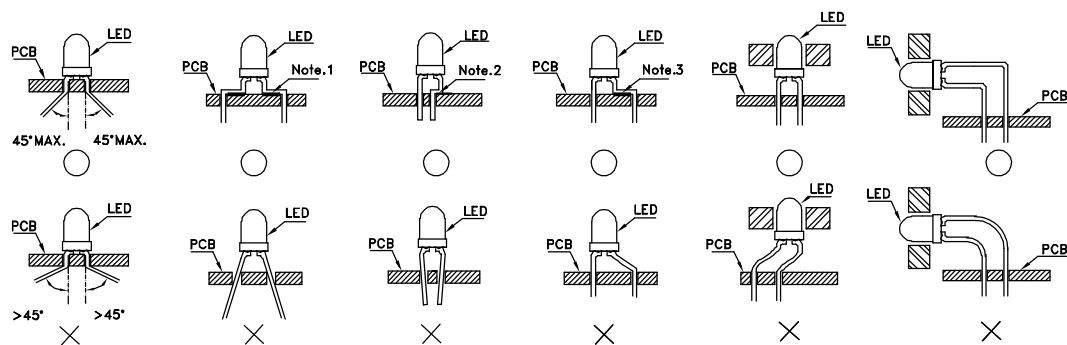


Fig.1

"○" Correct mounting method "X" Incorrect mounting method

Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

3. When soldering wires to the LED, each wire joint should be separately insulated with heat-shrink tube to prevent short-circuit contact. Do not bundle both wires in one heat shrink tube to avoid pinching the LED leads. Pinching stress on the LED leads may damage the internal structures and cause failure. (Fig. 2)

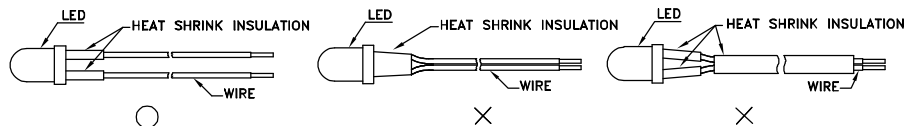


Fig. 2

4. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

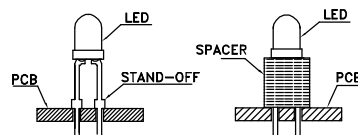


Fig. 3

Fig. 4

- Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

